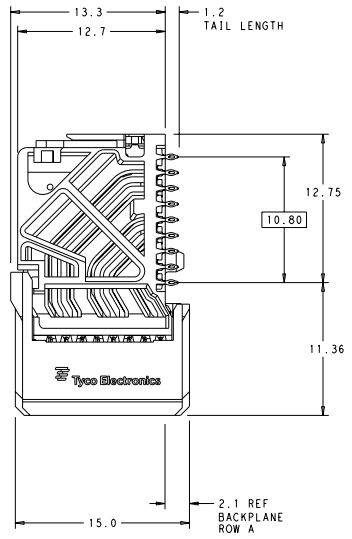
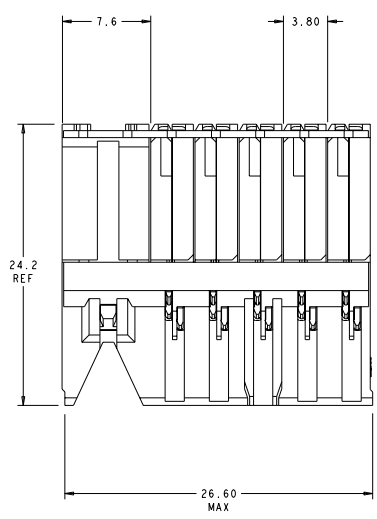
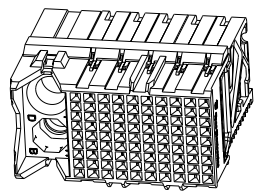


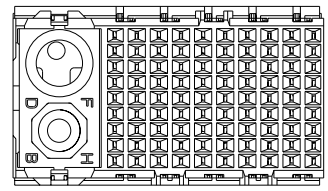
REV	DATE	DESCRIPTION	BY	CHK	APP
F		REVISED PER ECO-12-000417			



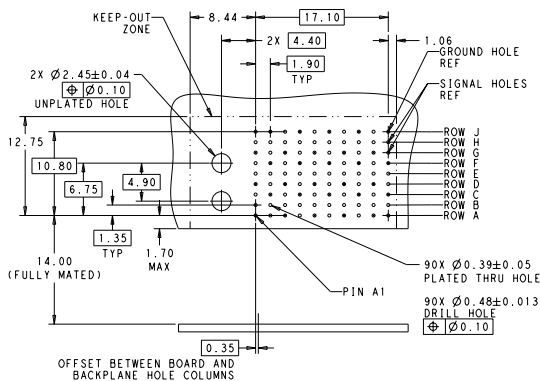
- △ MATERIAL:
HOUSING: LCP, GLASS FILLED, UL94V-0.
TERMINALS: HIGH PERFORMANCE COPPER ALLOY.
- △ FINISH:
30µ" SELECTIVE GOLD IN CONTACT AREA, SELECTIVE TIN
ON PCB TAILS, NICKEL OVERALL.
- △ FINISH:
30µ" SELECTIVE GOLD IN CONTACT AREA, SELECTIVE TIN-LEAD
ON PCB TAILS, NICKEL OVERALL.
- 4. CONNECTORS SUPPLIED WITH MOUNTING SCREWS.



SCALE 4:1



NONE	
A	E
B	F
C	G
D	H



RECOMMENDED PCB LAYOUT
MIN BOARD THICKNESS 1.0

REFER TO WWW.TE.COM
FOR PRODUCT AVAILABILITY

KEY POSITION	FINISH	PART NUMBER
H	△	8-2007703-5
G	△	7-2007703-5
F	△	6-2007703-5
E	△	5-2007703-5
D	△	4-2007703-5
C	△	3-2007703-5
B	△	2-2007703-5
A	△	1-2007703-5
NONE	△	2007703-5
H	△	8-2007703-1
G	△	7-2007703-1
F	△	6-2007703-1
E	△	5-2007703-1
D	△	4-2007703-1
C	△	3-2007703-1
B	△	2-2007703-1
A	△	1-2007703-1
NONE	△	2007703-1

THIS DRAWING IS A CONTROLLED DOCUMENT. DRAWING NO. 2007703-1

REV. 01

DATE 01/01/01

TE Connectivity

IMPACT, 3 PAIR, DAUGHTERCARD 10 COLUMN, LEFT GUIDED, SIGNAL MODULE, 0.39 ETELET

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